SPECIALLY FORMULATED TO DEBOND WAFERGRIP ADHESIVES

# StripAid™ X Series Specialty Solvent

NONHAZARDOUS FOR CLEAN, SAFE LABORATORY OPERATION

## StripAid™ X Series

StripAid is a biodegradable hydrocarbon used for debonding the temporary adhesive WaferGrip. The nonhazardous formulation makes StripAid a popular choice for processes in which environmental impact is a particular concern. StripAid can be used at ambient or elevated temperature and with ultrasonic agitation. In addition to debonding diced wafers, StripAid can be used to debond whole wafers, such as after the wafer thinning process.

Soak in StripAid at 110° C (5-20 min)

Soak in clean StripAid at 110° C (5-20 min)

Acetone rinse

**IPA** rinse

DI water rinse

## Safety

Because StripAid has a low order of toxicity, it does not require special handling. See the StripAid MSDS for complete safety, handling, storage and disposal information.

#### **Storage**

StripAid should be stored away from direct sunlight. Proper storage temperatures range from 20°C to 25°C. Do not store under freezing conditions.

#### StripAid X Specifications

Specific Gravity @ 68°F	0.97
Density @ 68°F, lbs/gallon	8.1
Solubility in Water	Negligible
Water Solubility in Strip Aid @25°C, % by weight	0.2
Absolute Viscosity 68°F, cSt	55
Flash Point, °C	212
Vapor Pressure	Negligible
Color	Cloudy
Odor	Mild



## Advantages of StripAid

- Non-Hazardous Customizable Process Convenient Packaging
  No Special Handling Specially Formulated to Remove WaferGrip
- dynatex M